

Title (en)

METHOD OF ACTIVATING SUBSTRATE SURFACES FOR ELECTROLESS METAL PLATING

Publication

EP 0081129 B1 19870114 (DE)

Application

EP 82110736 A 19821120

Priority

DE 3148280 A 19811205

Abstract (en)

[origin: US4764401A] A mild and simple process of activating substrate surfaces for the purpose of currentless metallization comprises using organometallic compounds of elements of the groups 1B and 8 of the Periodic System of Elements whose organic moiety has at least one functional group over and above the groups required for binding the metal are used for activation.

IPC 1-7

C23C 18/30

IPC 8 full level

C23C 18/30 (2006.01); **C23C 18/18** (2006.01); **C23C 18/28** (2006.01); **H05K 3/18** (2006.01)

CPC (source: EP US)

C23C 18/28 (2013.01 - EP US)

Cited by

DE3938710A1; EP0259754A3; CN108624907A; EP0564673A1; US5378268A; EP0195332A3; US4728560A; EP0146724A1; US4554183A; US5487964A; EP0146723A1; US4568571A; DE19941043A1; DE19941043B4; EP0166327A3; EP0153683A3; EP0166360B1; EP0082438B1; WO2019063859A1; WO2019063773A1; US10501852B2; EP3848483A2; US11898250B2

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DOCDB simple family (publication)

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EP 82110736 A 19821120; DE 3148280 A 19811205; DE 3275105 T 19821120; JP 21282082 A 19821206; US 770687 A 19870128